Please replace the paragraph appearing from page 16, line 22 to page 17, line 9, with the following replacement paragraph (a marked-up version of the paragraph, showing the changes made thereto, is attached):

It is preferable to adopt the structure that the electron-emitting apparatus further comprises a second wire different from the acceleration electrode disposed on an acceleration electrode substrate on which the acceleration electrode is formed, wherein the conductive contact member is electrically connected to both lead portions of the first and second wires. It is preferable to adopt the structure that at least a portion of the conductive B2 contact member is squeezed between the electron source substrate and the acceleration electrode substrate, and the conductive contact member is in contact with both lead portions of the first and second wires on the electron source substrate and on the acceleration electrode substrate.

Please replace the paragraph appearing at page 18, lines 6-26, with the following replacement paragraph (a marked-up version of the paragraph, showing the changes made thereto, is attached):

In supplying the first or second wire with a predetermined potential, B3 particularly a ground potential, it is preferable to adopt the structure that the predetermined potential is supplied from a cover of the electron-emitting apparatus. The cover is made conductive by using metal or covering it with a conductive film. It is preferable to adopt

the structure that the conductive contact member is electrically connected to the cover by fixing the cover to the conductive contact member (with screws, or pressure), and the predetermined potential such as a ground potential is supplied via the cover to the conductive contact member. The material of the cover is preferably aluminum or magnesium. It is preferable to form the cover by extruding. A conductive cover formed by coating a conductive layer on resin may also be used. The conductive layer preferably contains at least one of copper, nickel and carbon. It is preferable to adopt the structure that the conductive cover is connected to the common earth line of the power source of the electron-emitting apparatus.

B3 Cont.

Please replace the paragraph appearing from page 19, line 24 to page 20, line 8, with the following replacement paragraph (a marked-up version of the paragraph, showing the changes made thereto, is attached):

It is preferable to adopt the structure that an acceleration electrode substrate on which the acceleration electrode is formed constitutes a portion of a vacuum container, and the acceleration electrode has a conductive layer formed outside of the vacuum container. The conductive layer may be formed by attaching a film-like member to a substrate. This conductive layer is transparent if it is used with an image-forming apparatus and an image is viewed from the conductive layer side. It is preferable to use ITO (indium tin oxide) as the material of the conductive layer.

B4

Please replace the paragraph appearing at page 57, lines 15-24, with the following replacement paragraph (a marked-up version of the paragraph, showing the changes made thereto, is attached):

In Figs. 11 and 12, the reference numeral 1100 represents a contact plate which squeezes RP 1 constituting the vacuum container of the image display panel using electron-emitting devices and is electrically connected to the independent wire lead-in portion 108 on RP 1. The contact plate is made of material having conductivity and resilience and formed by bending a thin plate (thickness of 0.2 mm to 0.5 mm) such as stainless steel and phosphor bronze subjected to a plating process (anticorrosion process).

B5

Please replace the paragraph appearing from page 67, line 22 to page 68, line 25, with the following replacement paragraph (a marked-up version of the paragraph, showing the changes made thereto, is attached):

In this embodiment, as a thin flat image display panel, a display using electron-emitting devices is used. Similar to the above-described embodiments, in the high potential supply path from the high voltage source to the acceleration electrode of the face plate in the vacuum container, a dielectric breakdown proof structure using a high resistance film formed around the lead wire in the vacuum container on the RP side, as well as the ring shape independent wire (first wire) at the earth potential is provided. In this embodiment, another independent wire (second wire) spaced from the acceleration electrode is formed

B6

around the image forming unit (acceleration electrode) of FP in the vacuum container. The independent wire (second wire) at the earth potential is disposed at a constant space from the generally rectangular acceleration electrode and has a shape matching the generally rectangular acceleration electrode. In order to reliably define the earth potential of both independent wires (first and second wires), the RP independent wire is connected to the earth lines of FPC's connected to the earth potential of the driver circuits, and further a conductive contact member in contact with the inner wall of the front frame is used. The conductive contact member is in contact with the lead portions of both the RP and FP independent wires extended outside of the vacuum container to supply the earth potential, and is also electrically connected to the front frame connected to an earth potential of the power source unit. The conductive contact member is inserted and fixed in a space between FP and RP without using any fixing means such as a screw.

B6 cont.

Please replace the paragraph appearing at page 73, lines 5-18, with the following replacement paragraph (a marked-up version of the paragraph, showing the changes made thereto, is attached):

In RP 1, the independent wire 105 is connected to the earth lines of the X- and Y-direction FPC's 401-X and 401-Y connected to the earth patterns of the X- and Y-direction driver circuits. The lead-in portion of the independent wire 105 is exposed to the outside of the vacuum container in RP1, and in FP 11 the FP independent wire lead-in portion 50b of the independent wire 50a is exposed to the outside of the vacuum container.

B7